

REC

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FFICE. PLEASE RECORD THE ATTACHED

1. Name of conveying party(ies):
 (a) Yong Hwan Kwon
 (b) Sa Yoon Kang
 (c) Dong Hyeon Jang
 (d) Min Kyo Cho
 (e) Gu Sung Kim
 Additional name(s) of conveying party(ies) attached?
 Yes No

9.30.02

2. Name and address of receiving party(ies):
 Name: Samsung Electronics Co., Ltd.
 Address: 416, Maetan-dong
 Paldal-ku, Suwon city
 Kyungki-do
 Country: Republic of Korea

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2002 SEP 30 PM 1:30
FINANCE SECTION

3. Nature of Conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other
 Execution Date: September 3, 2002

Name and address of receiving party(ies):
 Name:
 Street Address:
 City: State:
 Country:
 Additional name(s) & address(es) attached?
 Yes No

4. Application number(s) or patent number(s):
 If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s) - 10/200,077
 Title: Wafer Level Stack Chip Package And Method For
 Manufacturing Same

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence
 concerning document should be mailed:
 Name: Norman R. Klivans
 Internal Address: SKJERVEN MORRILL LLP
 Street Address: 25 METRO DRIVE, SUITE 700
 City SAN JOSE State CA Zip 95110
 10/01/2002 6TON11 00000210 192386 10200077
 01 FC:581 40.00 CH

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00
 Authorized to be charged to Deposit Account 19-2386
 Charge Deposit Account 19-2386 for any additional fees
 required for this conveyance and credit deposit account
 19-2386 any amounts overpaid

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8. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Norman R. Klivans 33,003 Norman Klivans 9/25/02
 Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and documents: 2

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we Yong Hwan Kwon, Sa Yoon Kang, Dong Hyeon Jang, Min Kyo Cho and Gu Sung Kim, hereby sell, assign and transfer to **Samsung Electronics Co., Ltd**, a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-ku, Suwon-city Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in:

Wafer Level Stack Chip Package And Method For Manufacturing Same

for which we filed a United States Patent Application on July 18, 2002, which now has Serial No. 10/200,077, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 27th day of September, 2002.
Yong Hwan Kwon
 Yong Hwan Kwon

Executed this 27th day of September, 2002.
Sa Yoon Kang
 Sa Yoon Kang

Executed this 30th day of September, 2002.
Dong Hyeon Jang
 Dong Hyeon Jang

Executed this 30th day of September, 2002.
Min Kyo Cho
 Min Kyo Cho

Executed this 30th day of September, 2002.
Gu Sung Kim
 Gu Sung Kim

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